

# VUPB004R070NA

# **Datasheet**

### VUPB004R070NA

## **General Description**

$V_{(BR)DSS}$	R <sub>DS(ON)_max</sub>	$I_D$
4017	7.0mΩ@10V	00.4
40 V	10.5mΩ@4.5V	90A

## **Symbol**

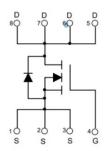
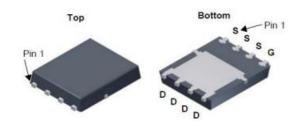


Figure 1 Symbol of VUPB004R070NA

#### **Features**

- Excellent R<sub>DS(on)</sub> and Low Gate Charge
- Trench Technology Power MOSFET
- Low Gate Resistance
- 100% UIS Tested

### Package Type



## **Application**

- DC/DC Converter
- Power Switching Application

PDFN5X6-8L

Figure 2 Package Type of VUPB004R070NA

## **Ordering Information**

Product Name	Package
VUPB004R070NA	PDFN5X6-8L



### VUPB004R070NA

## Absolute Maximum Ratings (T<sub>A</sub>= 25 °C, unless otherwise specified)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V <sub>DSS</sub>	40	V
Gate-Source Voltage		V <sub>GSS</sub>	±20	V
Continuous Drain Current Notel	$T_C=25$ °C	$I_D$	90	A
Continuous Drain Current Note6	$T_A = 25  ^{\circ}\mathrm{C}$	$I_D$	20	A
Pulsed Drain Current Note2		$I_{DM}$	180	A
Single Pulsed Avalanche Current <sup>Note3</sup>		I <sub>AS</sub>	40	A
Single Pulsed Avalanche Energy <sup>Note3</sup>		Eas	400	mJ
Total Power Dissipation Note5	T <sub>C</sub> = 25 °C	P <sub>D</sub>	70	W
Total Power Dissipation $^{Note6}$ $T_A=25$ $^{\circ}C$		P <sub>D</sub>	2.5	W
Junction Temperature		$T_{\rm J}$	150	°C
Storage Temperature		T <sub>STG</sub>	-55 to 150	°C

### **Thermal Resistance**

Parameter	Symbol	Min	Тур	Max	Unit
Thermal Resistance, Junction-to-Ambient Note6	$R_{ heta JA}$		50		°C/W
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$		1.8		°C/W



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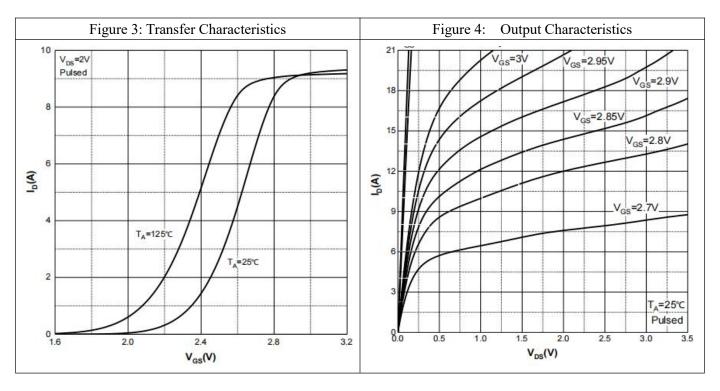
### Electrical Characteristics (T<sub>J</sub>= 25 °C, unless otherwise specified)

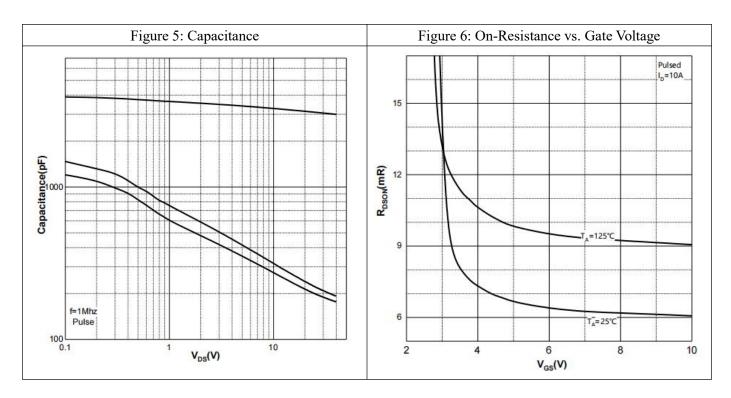
Parameter	Symbol	<b>Test Conditions</b>	Min	Тур	Max	Unit
Statistic Characteristics			•			
Drain-Source Breakdown Voltage	$\mathrm{BV}_{\mathrm{DSS}}$	$V_{GS}=0V, I_{D}=250uA$	40			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 32V, V_{GS} = 0V$			1	uA
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{DS}=V_{GS}$ , $I_D=250uA$	1.2	1.6	2.5	V
Static Drain-Source On-Resistance <sup>Note4</sup>	D	$V_{GS} = 10V, I_D = 10A$		5.5	7.0	mΩ
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}$ = 4.5V, $I_{D}$ = 10A		7.0	10.5	1112.2
Forward tranconductance <sup>Note4</sup>	gfs	$V_{DS} = 10V, I_D = 10A$		12		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=20V$		3163		pF
Output Capacitance	Coss	$V_{GS}=0V$		240		pF
Reverse Transfer Capacitance	$C_{RSS}$	f=1MHz		214		pF
Gate resistance	$R_{\rm g}$	f=1MHz,Open drain		1.59		Ω
Switching Parameters						
Total Gate Charge	$Q_g$	$V_{DS}=25V$		20		
Gate-source Charge	Qgs	$V_{GS}=10V$		9		пC
Gate-drain Charge	$Q_{gd}$	$I_D = 8A$		11		
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=15V$		15		
Turn-on Rise Time	$t_{\rm r}$	$V_{GS}=10V$		5		ns
Turn-off Delay Time	$t_{d(off)}$	$R_L=3\Omega$		50		
Turn-off Fall Time	$t_{\mathrm{f}}$	$R_{GEN}=3\Omega$		6		
<b>Diode Characteristics</b>						
Diode Forward Voltage Note3	$V_{ m DS}$	$V_{GS}=0V, I_{S}=10A$			1.2	V

#### Notes:

- 1. The maximum current rating is limited by package. And device mounted on a large heatsink
- 2. Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD} = 25V$ ,  $V_{GS} = 10V$ , L = 0.5mH,  $R_G = 25\Omega$  Starting  $T_J = 25$ °C.
- 4. Pulse Test : Pulse Width  $\leq 300 \mu s$ , duty cycle  $\leq 2\%$ .
- 5. The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^{\circ}C$ . And device mounted on a large heatsink
- 6.Device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25°C.

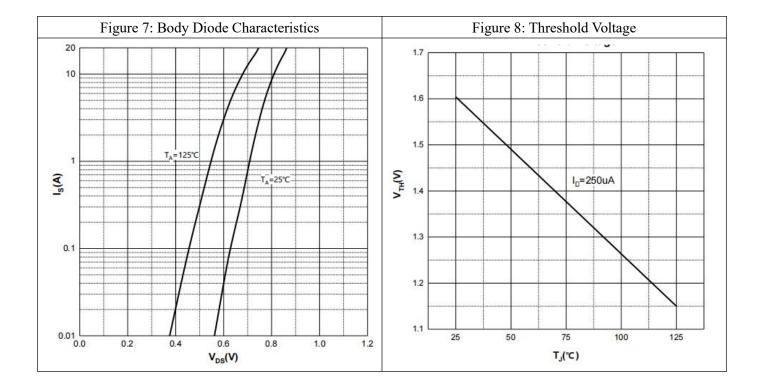
## **Typical Performance Characteristics**







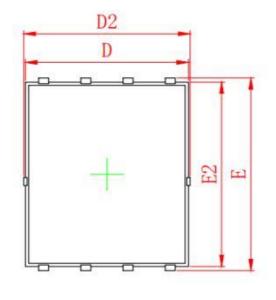
### VUPB004R070NA

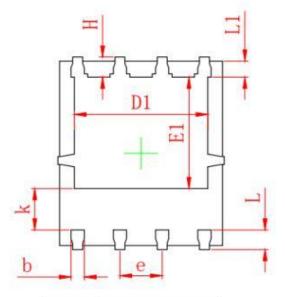


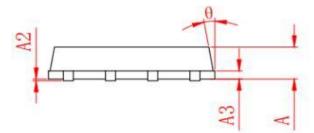


## **Mechanical Dimensions:**

### PDFN5X6-8L Package Information







SYMBOL.	MILLIMETER		
SIMBUL	MIN	MAX	
Α	0.900	1, 100	
A1	0. 254 REF.		
A2	0~0.05		
D	4. 824	4. 976	
D1	3.910	4. 110	
D2	4. 944	5. 076	
Е	5. 924	6.076	
E1	3. 375	3. 575	
E2	5. 674	5. 826	
b	0.350	0.450	
е	1. 270 TYP.		
L	0.534	0.686	
L1	0.424	0. 576	
k	1. 190 1. 39		
Н	0.549	0.701	
θ	8°	12"	



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## Via-Media Semiconductor Limited Company

### http://www.vmdsemi.com

#### **Main Sites:**

#### - Headquarters

Hangzhou Via-Media Semiconductor Co., LTD. 1305-1306, Building 71, No. 90, Wensan Road, Xihu District, Hangzhou, Zhejiang Province, P.R. China Tel: +86-0571-8515 0563

#### - Shanghai

Shanghai R&D Center. 1506~1508, Xinyin Building, 888 Yishan Road, Shanghai, P.R of China Tel: +86- 021-54201999

#### - Xi'an

Xi'an R&D Center 1703B, Building A, Greenland Center, Jinye Road, High-Tech Zone, Xi'an, Shaanxi, P.R of China

#### - Chengdu Office

Chengdu Winhi Semiconductor Co., LTD. Floor 15, Building 5, No. 171, Hele 2<sup>nd</sup> Street, Chengdu, Sichuan Province, P.R. China Tel: +86-028-8505 0771

#### - Shenzhen

Shenzhen Sales Center.
17B, No.1 Phoenix Building, 2008 Shennan Road,
Shenzhen, P.R of China
Tel: +86-0755- 82570682